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FORM PTO-15 102771246 ARTMENT OF COMMERCE

Patent and Trademark Office (Rev. 6-93) RECORDATION FORM COVER SHEET PATENTS ONLY Attorney Docket No.: 049128-5144 ATTN: MAIL STOP ASSIGNMENT To the Commissio **RECORDATION SERVICES** Please record the attached original documents or copy thereof. Name and address of receiving party(ies): 1. Name of conveying party(ies): Name: LG.PHILIPS LCD CO., LTD. (1) Byung Chul AHN (2) Byoung Ho LIM (3) Byeong Dae CHOI Street Address: 20, Yoido-dong, Youngdungpo-ku, Seoul, Korea Additional names of conveying party(ies) attached? Yes ⊠ No 3. Nature of conveyance: Additional name(s) & address(es) attached? Merger Change of Name Security Agreement ☐ Yes ☐ No Other Execution Date: (1)-(3) April 27, 2004 4. New Application number(s) or patent number(s): If this document is being filed together with a new application the execution date of the application is: B. Patent No.(s) 10/774,701 A. Patent Application No.(s) Additional numbers attached: ☐Yes ☒No Total number of applications and patents involved:  $\underline{1}$ Name and address of party to whom correspondence concerning document should be mailed: Total fee (37 C.F.R. §3.41): \_\_\$40.00 Enclosed Robert J. Gaybrick Name: Authorized to be charged to Deposit Account 50-0310 Internal Address: Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310 Customer No. 09629 (Attach duplicate page if paying by deposit account) Street Address: 1111 Pennsylvania Ave., N.W. City: Washington State: D.C. Zip: 20004 Statement and Signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. June 14, 2004 Robert J. Goodell Reg. No. 41,040 Date Name of Person Signing Total number of pages including cover sheet, attachments and documents: 3

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ATTORNEY DOCKET NO.: 049128-5144 SOLE/JOINT INVENTION (U.S. Rights Only)

## ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled.

METHOD OF PATTERNING TRANSPARENT CONDUCTIVE FILM, THIN FILM TRANSISTOR SUBSTRATE USING THE SAME AND FABRICATING METHOD THEREOF

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on February 10, 2004, (Serial No. 10/774,701); and

WHEREAS, LG.Philips LCD Co., Ltd., a corporation of Korea, whose post office address is 20. Yoido-dong, Youngdungpo-ku. Seoul, Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. 10/774,701, filed February 10, 2004) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s). Full Name of Sole or First Assignor Assignor's Signature Byung Chul AHN myu Address #203-903, Hyangchon Apartment, 899-2. Pyungchon-dong, Dongan-ku, Citizenship Ahnyang-shi, Kyounggi-do, Korea Korea Full Name of Second Assignor Assignor's Signature Date Byoung Ho LIM Anr 2 #102-103, Park Mansion, Doryang-dong, Address Citizenship Kyoungsangbuk-do, Korea Korca Names of additional inventors attached XYes No.

1-WA/2133330.1

PATENT REEL: 015464 FRAME: 0118

Full Name of Third Assignor	Assignor's Signature	Date
Byeong Dae CHOI	Bycoma Dae Chai	Apr27.2004
Address 651-18, Sinam 4-dong, Dong-ku, Daegu, Korea		Citizenship
		Korea
Names of additional inventors attached Yes No		

1-WA/2133330.1

TOTAL P.08

PATENT REEL: 015464 FRAME: 0119